SN74LS273

Octal D Flip-Flop with Clear

The SN74LS273 is a high-speed 8-Bit Register. The register consists of eight D-Type Flip-Flops with a Common Clock and an asynchronous active LOW Master Reset. This device is supplied in a 20-pin package featuring 0.3 inch lead spacing.

- 8-Bit High Speed Register
- Parallel Register
- Common Clock and Master Reset
- Input Clamp Diodes Limit High-Speed Termination Effects

GUARANTEED OPERATING RANGES

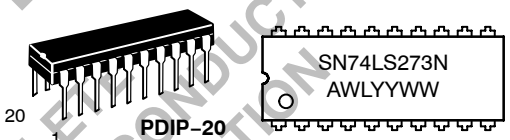
Symbol	Parameter	Min	Typ	Max	Unit
V_{CC}	Supply Voltage	4.75	5.0	5.25	V
T_A	Operating Ambient Temperature Range	0	25	70	°C
I_{OH}	Output Current – High			–0.4	mA
I_{OL}	Output Current – Low			8.0	mA

ON Semiconductor

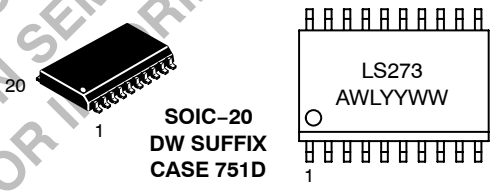
http://onsemi.com

LOW POWER SCHOTTKY

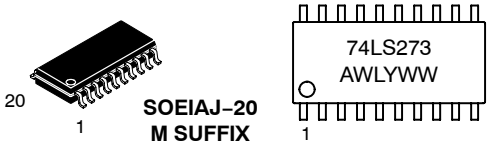
MARKING DIAGRAMS



PDIP–20
N SUFFIX
CASE 738



SOIC–20
DW SUFFIX
CASE 751D



SOEIAJ–20
M SUFFIX
CASE 967

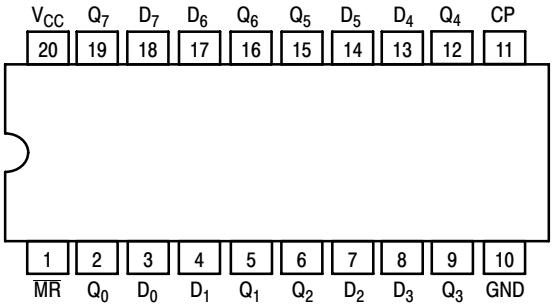
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
SN74LS273N	PDIP–20	1440 Units/Box
SN74LS273DW	SOIC–WIDE	38 Units/Rail
SN74LS273DWR2	SOIC–WIDE	2500/Tape & Reel
SN74LS273M	SOEIAJ–20	See Note 1
SN74LS273MEL	SOEIAJ–20	See Note 1

1. For ordering information on the EIAJ version of the SOIC package, please contact your local ON Semiconductor representative.

CONNECTION DIAGRAM DIP (TOP VIEW)



PIN NAMES		LOADING (Note a) HIGH	LOW
CP	Clock (Active HIGH Going Edge) Input	0.5 U.L.	0.25 U.L.
$D_0 - D_7$	Data Inputs	0.5 U.L.	0.25 U.L.
$\overline{MR}$	Master Reset (Active LOW) Input	0.5 U.L.	0.25 U.L.
$Q_0 - Q_7$	Register Outputs	10 U.L.	5 U.L.

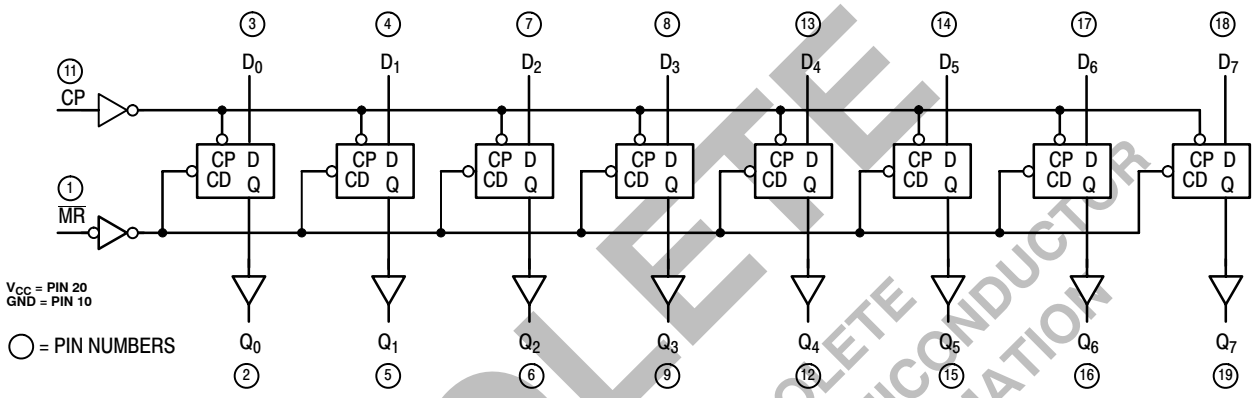
NOTES:
a) 1 TTL Unit Load (U.L.) = 40 μA HIGH/1.6 mA LOW.

TRUTH TABLE

$\overline{MR}$	CP	D_x	Q_x
L	X	X	L
H	↑	H	H
H	↑	L	L

H = HIGH Logic Level
L = LOW Logic Level
X = Immaterial

LOGIC DIAGRAM



FUNCTIONAL DESCRIPTION

The SN74LS273 is an 8-Bit Parallel Register with a common Clock and common Master Reset.

When the $\overline{MR}$ input is LOW, the Q outputs are LOW, independent of the other inputs. Information meeting the setup and hold time requirements of the D inputs is transferred to the Q outputs on the LOW-to-HIGH transition of the clock input.

DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

Symbol	Parameter	Limits Min	Typ	Max	Unit	Test Conditions	
V_{IH}	Input HIGH Voltage	2.0			V	Guaranteed Input HIGH Voltage for All Inputs	
V_{IL}	Input LOW Voltage			0.8	V	Guaranteed Input LOW Voltage for All Inputs	
V_{IK}	Input Clamp Diode Voltage		−0.65	−1.5	V	V_{CC} = MIN, I_{IN} = −18 mA	
V_{OH}	Output HIGH Voltage	2.7	3.5		V	V_{CC} = MIN, I_{OH} = MAX, V_{IN} = V_{IH} or V_{IL} per Truth Table	
V_{OL}	Output LOW Voltage		0.25	0.4	V	I_{OL} = 4.0 mA	V_{CC} = V_{CC} MIN, V_{IN} = V_{IL} or V_{IH} per Truth Table
			0.35	0.5	V	I_{OL} = 8.0 mA	
I_{IH}	Input HIGH Current			20	μA	V_{CC} = MAX, V_{IN} = 2.7 V	
				0.1	mA	V_{CC} = MAX, V_{IN} = 7.0 V	
I_{IL}	Input LOW Current			−0.4	mA	V_{CC} = MAX, V_{IN} = 0.4 V	
I_{OS}	Short Circuit Current (Note 2)	−20		−100	mA	V_{CC} = MAX	
I_{CC}	Power Supply Current			27	mA	V_{CC} = MAX	

2. Not more than one output should be shorted at a time, nor for more than 1 second.

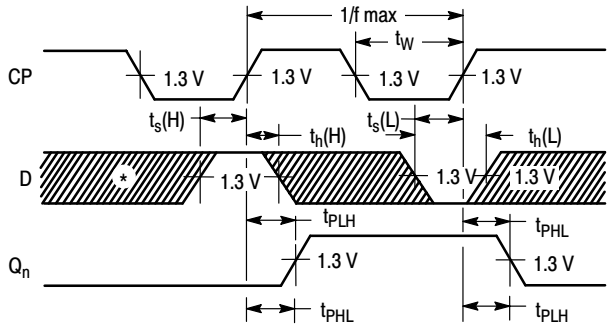
AC CHARACTERISTICS (T_A = 25°C, V_{CC} = 5.0 V)

Symbol	Parameter	Limits Min	Typ	Max	Unit	Test Conditions
f_{MAX}	Maximum Input Clock Frequency	30	40		MHz	Figure 1
t_{PHL}	Propagation Delay, $\overline{MR}$ to Q Output		18	27	ns	Figure 2
t_{PLH} t_{PHL}	Propagation Delay, Clock to Output		17 18	27 27	ns	Figure 1

AC SETUP REQUIREMENTS (T_A = 25°C, V_{CC} = 5.0 V)

Symbol	Parameter	Limits Min	Typ	Max	Unit	Test Conditions
t_w	Pulse Width, Clock or Clear	20			ns	Figure 1
t_s	Data Setup Time	20			ns	Figure 1
t_h	Hold Time	5.0			ns	Figure 1
t_{rec}	Recovery Time	25			ns	Figure 2

AC WAVEFORMS



*The shaded areas indicate when the input is permitted to change for predictable output performance.

Figure 1. Clock to Output Delays, Clock Pulse Width, Frequency, Setup and Hold Times Data to Clock

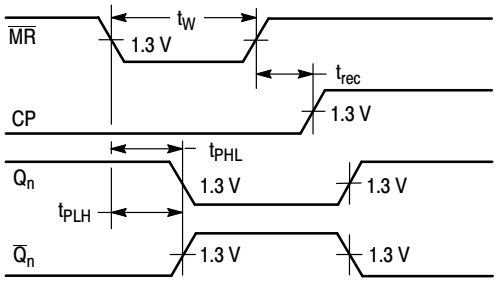


Figure 2. Master Reset to Output Delay, Master Reset Pulse Width, and Master Reset Recovery Time

DEFINITION OF TERMS

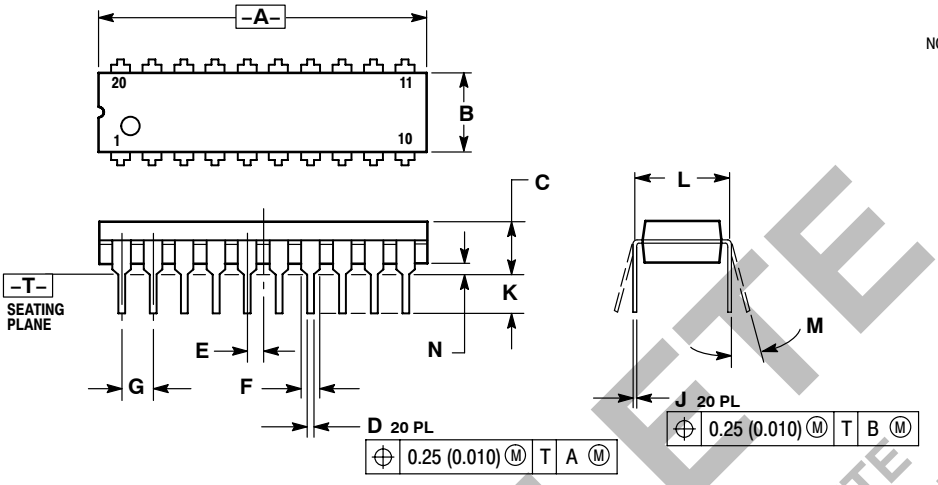
SETUP TIME (t_s) — is defined as the minimum time required for the correct logic level to be present at the logic input prior to the clock transition from LOW-to-HIGH in order to be recognized and transferred to the outputs.

HOLD TIME (t_h) — is defined as the minimum time following the clock transition from LOW-to-HIGH that the logic level must be maintained at the input in order to ensure continued recognition. A negative HOLD TIME indicates that the correct logic level may be released prior to the clock transition from LOW-to-HIGH and still be recognized.

RECOVERY TIME (t_{rec}) — is defined as the minimum time required between the end of the reset pulse and the clock transition from LOW-to-HIGH in order to recognize and transfer HIGH data to the Q outputs.

PACKAGE DIMENSIONS

N SUFFIX
PLASTIC PACKAGE
CASE 738–03
ISSUE E

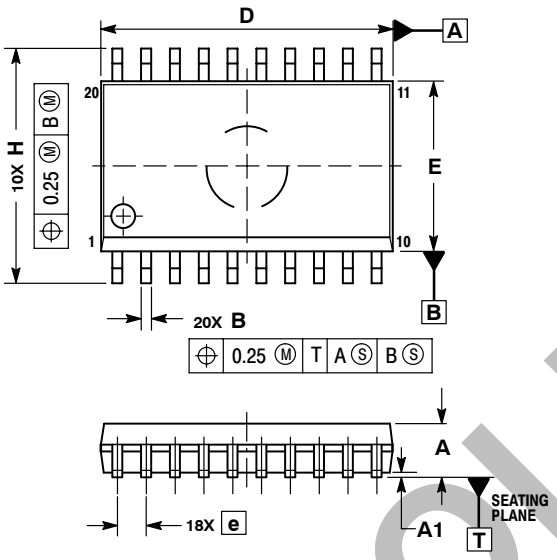


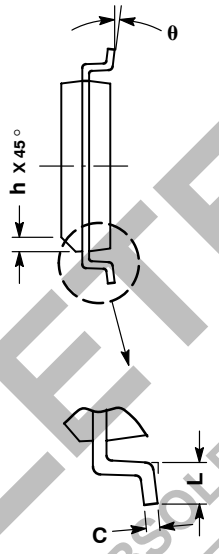
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	1.010	1.070	25.66	27.17
B	0.240	0.260	6.10	6.60
C	0.150	0.180	3.81	4.57
D	0.015	0.022	0.39	0.55
E	0.050 BSC		1.27 BSC	
F	0.050	0.070	1.27	1.77
G	0.100 BSC		2.54 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.140	2.80	3.55
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

PACKAGE DIMENSIONS

D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751D–05
ISSUE F



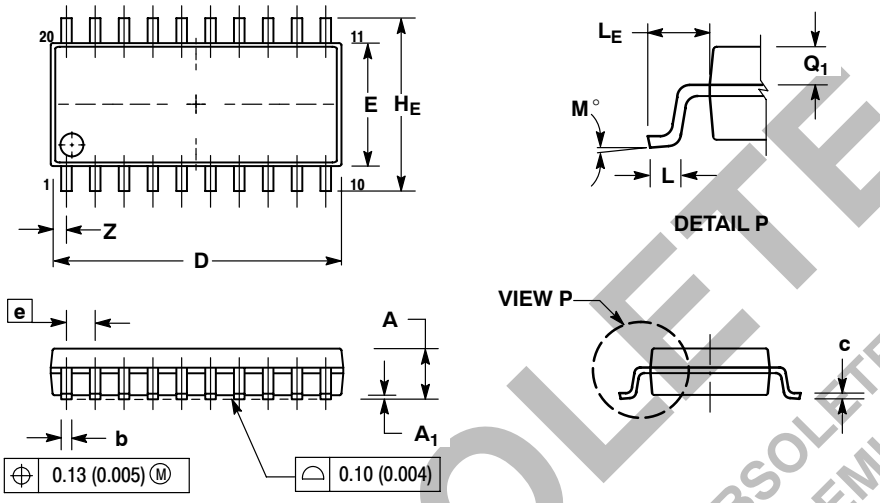


NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS	
DIM	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
B	0.35	0.49
C	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
θ	0°	7°

PACKAGE DIMENSIONS

M SUFFIX
SOEIAJ PACKAGE
CASE 967–01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	12.35	12.80	0.486	0.504
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z	---	0.81	---	0.032

PUBLICATION ORDERING INFORMATION

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SN74LS273/D